

CSOIC

Ceramic Small Outline Integrated Circuit Package (CSOIC)

This is a ceramic version of the Plastic SOIC package. The CSOIC is a hermetic package consisting of a multilayer ceramic surrounding a "gullwing" formed leadframe. This package has leads extending from two sides of the package (dual). The package is hermetically solder sealed at 325° Centigrade. These IC packages have proven surface mount (SMT) performance characteristics and have been designed to adapt easily to ALL SMT processes and lines. Ceramic SOIC packages provide component and packaging engineers the ability and freedom to optimize systems and product designs.

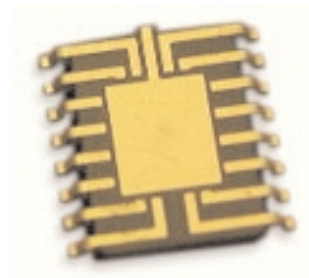
Features:

The CSOIC offers a variety of features:

- 28 lead count (Others available if supplied and tooled)
- 300 mil body size
- Hermetic solder sealed package
- High thermal conductive ceramic
- Gold lead finish
- "Gullwing" lead form
- JEDEC and EIAJ package outline standard compliant
- Wide selection of cavity sizes to meet most die size needs
- Commercial or full Military flows

Applications:

End products range from consumer (audio, video, and entertainment), telecom (pagers, cordless telephone), RF/wireless (PC cards, RF/CATV, telemetry), office (fax, copier, and printer), PC/peripheral, automotive and other applications. Whether you're working with resistor networks, discrete semiconductors or ICs, CSOIC package product lines will serve the needs of various semiconductor technologies with ease.



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